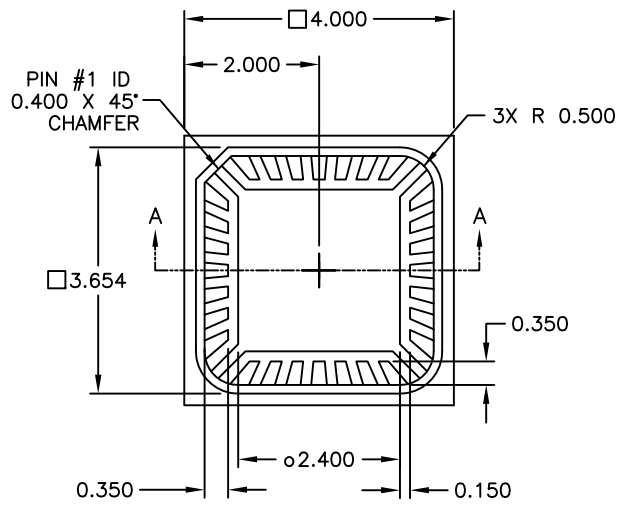
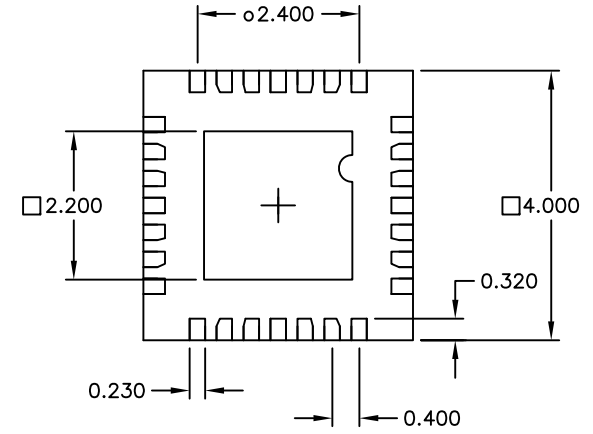
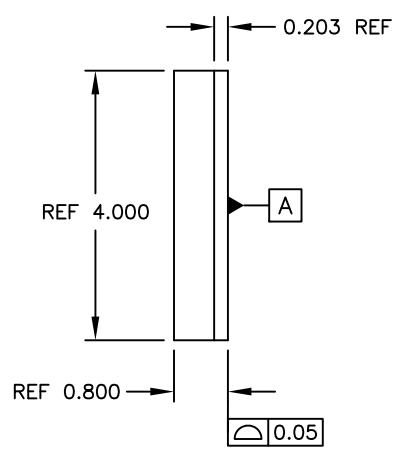


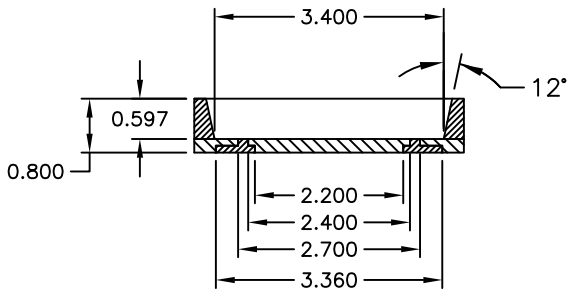
REVISIONS			
ECN NO.	DATE	DESCRIPTION	APPROVED
		PRODUCTION RELEASE	



TOP VIEW



BOTTOM VIEW



SECTION A-A

NOTES

- MATERIALS:  
LEAD FRAME: COPPER 194FH, THK = 0.203±0.008  
BODY: SEMICONDUCTOR MOLDING EPOXY, CONTACT SPECTRUM FOR DETAILS.
- FINISH:  
LEAD FRAME: ELECTROLESS NICKEL PER MIL-C-26074, CLASS 1, 100 TO 300 MICROINCHES (2.5um - 7.6um) THICK.  
GOLD PLATE PER MIL-G-45204, TYPE 3, GRADE A, CLASS 1 (40 TO 80 MICROINCHES (1um - 2um) THICK).  
BODY SURFACE FINISH: VDI 21-24 (1.12-1.6 Ra).
- PACKAGE MISMATCH: BODY OFFSET TO LEAD FRAME = 0.076mm MAX
- UNLESS OTHERWISE SPECIFIED, RADIUS ON ALL MOLDED EDGES AND CORNERS = 0.25mm MAX.
- PACKAGE CONFORMS TO JEDEC MO-220.

**Spectrum Semiconductor Materials, Inc.**  
[www.spectrum-semi.com](http://www.spectrum-semi.com)  
 155 Nicholson Lane  
 San Jose, CA 95134  
 PHONE: (408) 435-5555 FAX: (408) 435-8226

4mm x 4mm  
 QFN 28 LEAD OmPP

 THIRD ANGLE PROJECTION UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETER TOLERANCES ARE: X.XX ± 0.15 X.XXXX ± ---- X.XXX ± 0.050 ANGLES: ± 1° <b>DO NOT SCALE DRAWING</b>	DRAWN BY: MWK DATE: 12/3/2014
	APP BY: SJO DATE: 12/3/2014
MADE IN USA	

SIZE: A	PART NO.: QFN02806	REV: REV
SCALE:	CAD FILE:	SHEET 1 OF 1